2811

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#9/A
4-4-01
R. Drake

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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OCT 13 2000
PATENT & TRADEMARK OFFICE
JC89

Applicants: KAJIHARA, et al.

Serial No.: 09/328,910

Filed: June 9, 1999

For: LEADFRAME, SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE USING THE SAME, AND METHOD OF AND PROCESS FOR FABRICATING THE TWO

Art Unit: 2811

Examiner: unassigned

PRELIMINARY AMENDMENT

Assistant Commissioner
for Patents
Washington, D.C. 20231

October 13, 2000

Sir:

The following is respectfully submitted in connection with the above-identified application.

RECEIVED
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TC 2800 MAIL ROOM

IN THE CLAIMS:

Please add the following new claims:

-- 63. A semiconductor device comprising:

(1) a semiconductor chip having a main surface and a rear surface opposite to said main surface, said semiconductor chip having a plurality of semiconductor elements and bonding pads formed on said main surface;

(2) a lead frame including:

10/23/2000 MMARMOL 00000001 09328910
01 FC:102 160.00 OP
02 FC:103 180.00 OP